



STB70NF3LL

N-CHANNEL 30V - 0.008 Ω - 70A D²PAK LOW GATE CHARGE STripFET™ POWER MOSFET

PRELIMINARY DATA

TYPE	V _{DSS}	R _{D(on)}	I _D
STB70NF3LL	30 V	<0.01 Ω	70 A

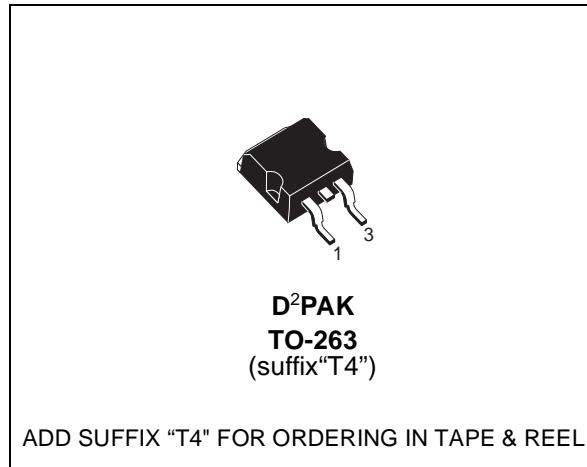
- TYPICAL R_{D(on)} = 0.01 Ω @ 4.5 V
- OPTIMAL R_{D(on)} x Q_G TRADE-OFF @ 4.5 V
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED

DESCRIPTION

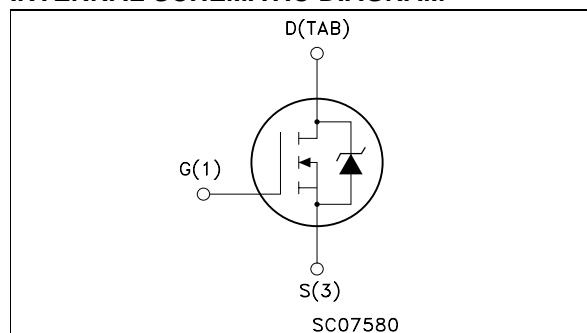
This application specific Power Mosfet is the third generation of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

APPLICATIONS

- SPECIFICALLY DESIGNED AND OPTIMISED FOR HIGH EFFICIENCY CPU CORE DC/DC CONVERTERS



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	30	V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 kΩ)	30	V
V _{GS}	Gate- source Voltage	±16	V
I _D	Drain Current (continuos) at T _C = 25°C	70	A
I _D	Drain Current (continuos) at T _C = 100°C	50	A
I _{DM(•)}	Drain Current (pulsed)	280	A
P _{tot}	Total Dissipation at T _C = 25°C	100	W
	Derating Factor	0.67	W/°C
T _{stg}	Storage Temperature	-65 to 175	°C
T _j	Max. Operating Junction Temperature	175	°C

(•)Pulse width limited by safe operating area

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THERMAL DATA

$R_{thj\text{-}case}$	Thermal Resistance Junction-case Max	Max	1.5	$^{\circ}\text{C}/\text{W}$
$R_{thj\text{-}amb}$	Thermal Resistance Junction-ambient Max	Max	62.5	$^{\circ}\text{C}/\text{W}$
T_j	Maximum Lead Temperature For Soldering Purpose		300	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS ($T_{\text{case}} = 25^{\circ}\text{C}$ unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source Breakdown Voltage	$I_D = 250 \mu\text{A}$ $V_{GS} = 0$	30			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating}, T_C = 125^{\circ}\text{C}$			1 10	μA μA
I_{GSS}	Gate-body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 16 \text{ V}$			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250 \mu\text{A}$	1		2.5	V
$R_{DS(\text{on})}$	Static Drain-source On Resistance	$V_{GS} = 10 \text{ V}$ $I_D = 35 \text{ A}$ $V_{GS} = 4.5 \text{ V}$ $I_D = 18 \text{ A}$		0.008 0.01	0.01 0.012	Ω Ω
$I_{D(\text{on})}$	On State Drain Current	$V_{DS} > I_{D(\text{on})} \times R_{DS(\text{on})\text{max}}$ $V_{GS} = 10 \text{ V}$	70			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(*)}$	Forward Transconductance	$V_{DS} > I_{D(\text{on})} \times R_{DS(\text{on})\text{max}}$ $I_D=35 \text{ A}$		40		S
C_{iss} C_{oss} C_{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitances	$V_{DS} = 25 \text{ V}$ $f = 1 \text{ MHz}$ $V_{GS} = 0$		1700 500 115		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)**SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Delay Time Rise Time	$V_{DD} = 15 \text{ V}$ $I_D = 35 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 4.5 \text{ V}$ (see test circuit, Figure 3)		20 350		ns ns
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 24 \text{ V}$ $I_D = 70 \text{ A}$ $V_{GS} = 10 \text{ V}$		43 10 10	56	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$ t_f	Turn-off Delay Time Fall Time	$V_{DD} = 15 \text{ V}$ $I_D = 35 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 4.5 \text{ V}$ (Resistive Load, see fig.3)		35 65		ns ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM(\bullet)}$	Source-drain Current Source-drain Current (pulsed)				70 280	A A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 70 \text{ A}$ $V_{GS} = 0$			1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 70 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 15 \text{ V}$ $T_j = 150 \text{ }^\circ\text{C}$ (see test circuit, Figure 5)		40 52 2.4		ns nC A

(*)Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

(*)Pulse width limited by safe operating area.

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Fig. 1: Unclamped Inductive Load Test Circuit

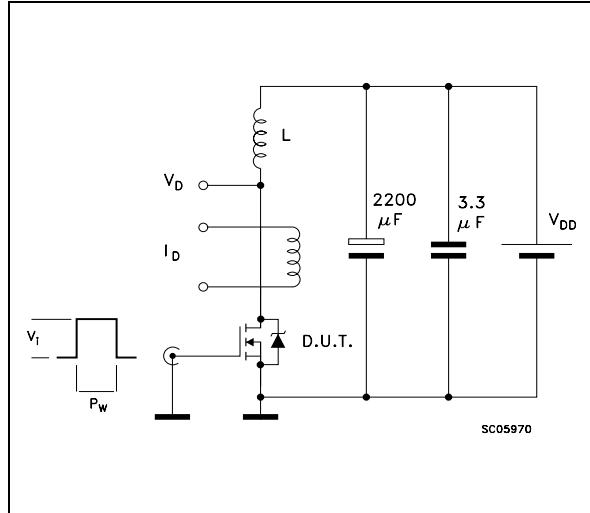


Fig. 2: Unclamped Inductive Waveform

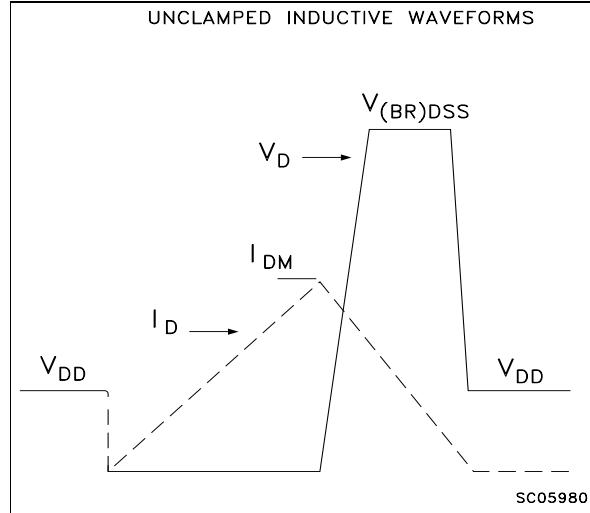


Fig. 3: Switching Times Test Circuits For Resistive Load

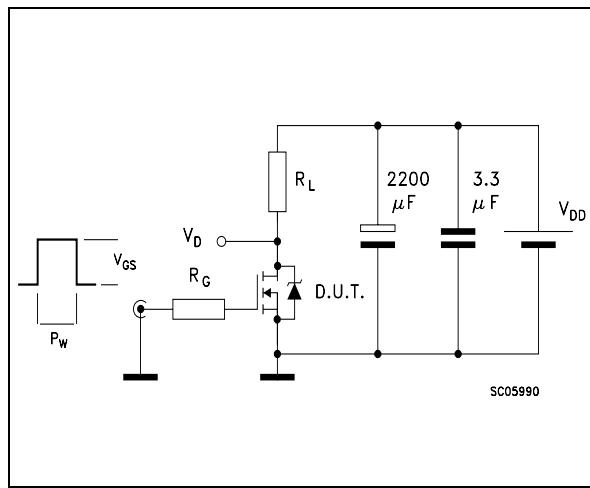


Fig. 4: Gate Charge test Circuit

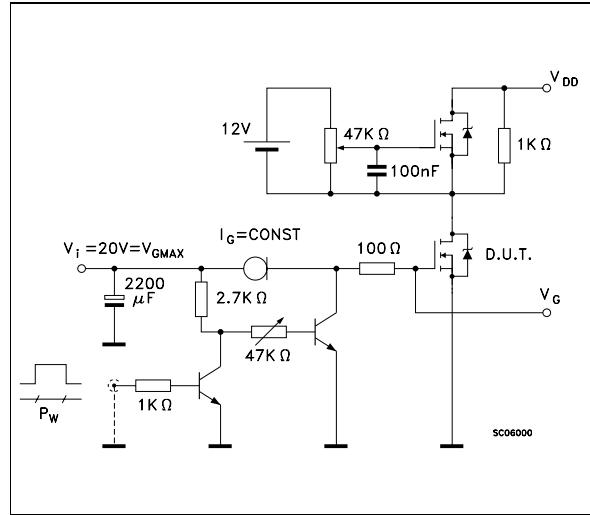
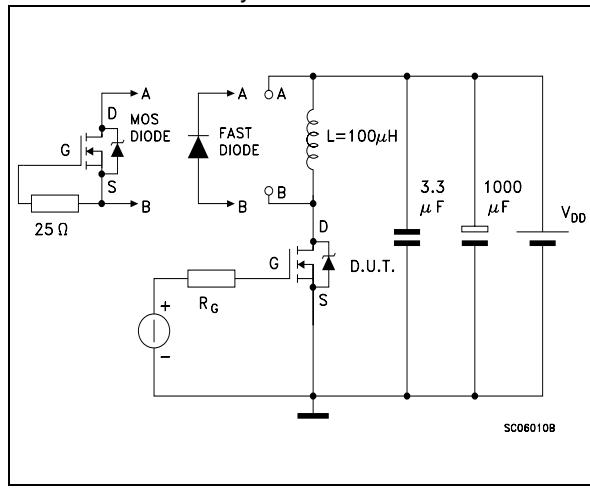
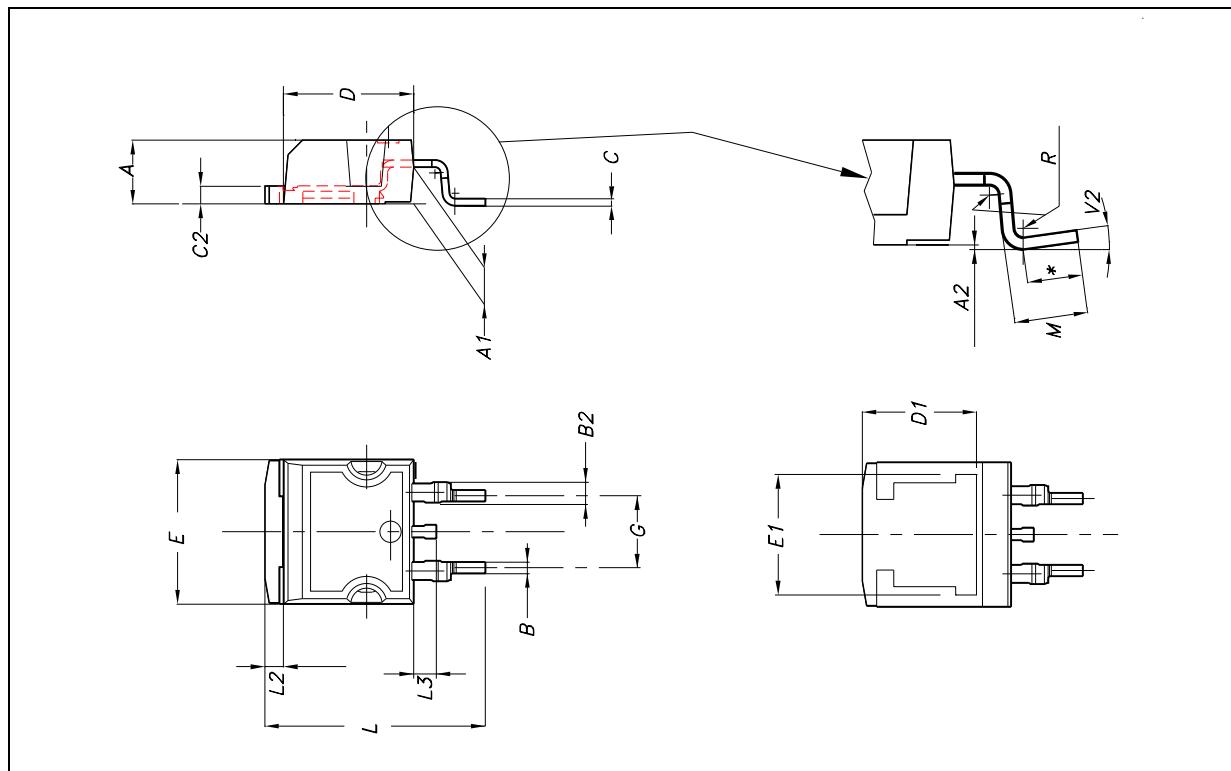


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times



D²PAK MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0°		8°			



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